# Triple-Output TFT LCD Power Supply with Fault Protection 


#### Abstract

General Description The MAX1889 provides the three regulated output voltages required for active matrix, thin-film transistor liquid crystal displays (TFT LCDs). It combines a high-performance step-up regulator with two linear-regulator controllers and multiple levels of protection circuitry for a complete power-supply system. The main DC-DC converter is a high-frequency ( $500 \mathrm{kHz} / 1 \mathrm{MHz}$ ), current-mode step-up regulator with an integrated N -channel power MOSFET that allows the use of ultra-small inductors and ceramic capacitors. With its high closed-loop bandwidth performance, the MAX1889 provides fast transient response to pulsed loads while operating with efficiencies over $85 \%$. The positive and negative linear-regulator controllers postregulate charge-pump outputs for TFT gate-on and gate-off supplies. The MAX1889 has a unique input switch control that can replace the typical input fuse by disconnecting the load from the input supply when a fault is detected. The fault detector monitors all three regulated output voltages and can monitor current from the input supply as well. Additionally, the MAX1889 enters thermal shutdown when its overtemperature threshold is reached. The MAX1889 undervoltage lockout is set at 2.5 V (max) to allow the input supply to droop under pulsed load conditions while avoiding any unexpected behavior when its input voltage dips momentarily. Also, the builtin soft-start and cycle-by-cycle current limiting prevent input surge currents during power-up. The MAX1889 is available in a 16-pin thin QFN package with a maximum thickness of 0.8 mm for ultra-thin LCD panel design.


Applications

Notebook Computer Displays
LCD Monitors
Car Navigation Displays
High-Performance Step-Up Regulator
Fast Transient Response
Current-Mode Control Architecture
Built-In High-Efficiency N-Channel Power
MOSFET
Current-Limit Comparator
>85\% Efficiency
Selectable Switching Frequency
(500kHz/1 MHz)
Internal Soft-Start
Positive Linear-Regulator Controller
Negative Linear-Regulator Controller
Triple-Level Protection Against Smoke or Fire
Input Switch Replaces Input Fuse
Output Overload Detection with Timer Latch
Thermal Shutdown
2.7V to 5.5V Input Operating Range
Ultra-Small External Components
1 1 A Shutdown Current (max)
1mA Quiescent Current (max)
Ultra-Thin 16-Pin QFN Package
(0.8mm Maximum Thickness)

Features

- High-Performance Step-Up Regulator Fast Transient Response Current-Mode Control Architecture MOSFET
Current-Limit Comparator >85\% Efficiency ( $500 \mathrm{kHz} / 1 \mathrm{MHz}$ ) Internal Soft-Start
- Positive Linear-Regulator Controller
- Negative Linear-Regulator Controller
- Triple-Level Protection Against Smoke or Fire Input Switch Replaces Input Fuse Output Overload Detection with Timer Latch Thermal Shutdown
- 2.7V to 5.5V Input Operating Range
- Ultra-Small External Components
- $1 \mu \mathrm{~A}$ Shutdown Current (max)
- 1mA Quiescent Current (max)
- Ultra-Thin 16-Pin QFN Package ( 0.8 mm Maximum Thickness)

Ordering Information

| PART | TEMP RANGE | PIN-PACKAGE |
| :--- | :--- | :--- |
| MAX1889ETE | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 16 Thin QFN $(5 \mathrm{~mm} \times 5 \mathrm{~mm})$ |
| MAX1889EGE | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 16 QFN $(5 \mathrm{~mm} \times 5 \mathrm{~mm})$ |

* Future product-Contact factory for availability.

Pin Configuration


## Triple-Output TFT LCD Power Supply with Fault Protection

## ABSOLUTE MAXIMUM RATINGS

IN, $\overline{\text { SHDN, OCN, OCP, }}$
FB, FBP, FBN, FREQ to GND ...............................-0.3V to +6 V
PGND to GND $\pm 0.3 \mathrm{~V}$
LX to PGND
-0.3 V to +14 V
DRVP to GND. $-0.3 V$ to $+30 V$
REF, GATE, TGND to GND ...........................-0.3V to (VIN +0.3 V )
DRVN to GND .....................................(VIN -28 V ) to (VIN +0.3 V )

| Continuous Power Dissipation $\left(\mathrm{T}_{\mathrm{A}}=+70^{\circ} \mathrm{C}\right)$ 16-Pin QFN (derate $19.2 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ above $+70^{\circ} \mathrm{C}$ ) | .. 1538 mW |
| :---: | :---: |
| Operating Temperature Range |  |
| MAX1889EGE ............................................-40 | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ |
| Junction Temperature | $+150^{\circ} \mathrm{C}$ |
| Storage Temperature Range ..........................-65 | $65^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$ |
| Lead Temperature (soldering, | $+300^{\circ}$ |

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## ELECTRICAL CHARACTERISTICS

$\left(V_{I N}=3 V, \overline{S H D N}=I N, C_{R E F}=0.22 \mu F, P G N D=G N D, T_{A}=\mathbf{0}^{\circ} \mathbf{C}\right.$ to $+85^{\circ} \mathbf{C}$. Typical values are at $T_{A}=+25^{\circ} \mathrm{C}$, unless otherwise noted. $)$

| PARAMETER | SYMBOL | CONDITIONS |  | MIN | TYP | MAX | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| IN Supply Range | VIN |  |  | 2.7 |  | 5.5 | V |
| IN Undervoltage Lockout (UVLO) Threshold | VuVLo | 350mV typical hysteresis | VIN rising | 2.55 | 2.7 | 2.85 | V |
|  |  |  | $\mathrm{V}_{\text {IN }}$ falling | 2.2 | 2.35 | 2.5 |  |
| IN Quiescent Current | IIN | $\mathrm{V}_{\text {FB }}=\mathrm{V}_{\text {FBP }}=1.5 \mathrm{~V}, \mathrm{~V}_{\text {FBN }}=0 \mathrm{~V}$ (Note 1) |  |  |  | 1.0 | mA |
| IN Shutdown Current |  | $V_{\text {SHDN }}=0, \mathrm{~V}_{\text {IN }}=5 \mathrm{~V}$ |  |  | 0.1 | 1.0 | $\mu \mathrm{A}$ |
| REF Output Voltage | VREF | $-2 \mu \mathrm{~A}$ < IREF $<50 \mu \mathrm{~A}$ |  | 1.231 | 1.250 | 1.269 | V |
| Thermal Shutdown |  |  |  |  | 160 |  | ${ }^{\circ} \mathrm{C}$ |
| MAIN STEP-UP REGULATOR |  |  |  |  |  |  |  |
| Main Output Voltage Range | VMAIN |  |  | VIN |  | 13 | V |
| Operating Frequency | fosc | $\mathrm{V}_{\text {FREQ }}=\mathrm{V}_{\text {IN }}$ |  | 0.85 | 1 | 1.15 | MHz |
|  |  | $V_{\text {FREQ }}=0 \mathrm{~V}$ |  | 500 |  |  | kHz |
| Oscillator Maximum Duty Cycle |  |  |  | 80 | 85 | 90 | \% |
| FB Regulation Voltage | $V_{\text {FB }}$ | ILX $=200 \mathrm{~mA}$, slope $=0$ ( Note 2) |  | 1.229 | 1.242 | 1.254 | V |
| FB Fault Trip Level |  | $V_{\text {FB }}$ falling |  | 0.95 | 1.0 | 1.05 | V |
| Load Regulation |  | IMAIN $=0$ to full load |  |  | -1.6 |  | \% |
| Line Regulation |  | $\mathrm{V}_{\mathrm{IN}}=2.7 \mathrm{~V}$ to 5.5 V |  |  | 0.2 |  | \%/V |
| FB Input Bias Current | IFB | $\mathrm{V}_{\mathrm{FB}}=1.5 \mathrm{~V}$ |  | -100 |  | +100 | nA |
| LX Switch On-Resistance | RLX(ON) |  |  |  | 250 | 450 | $\mathrm{m} \Omega$ |
| LX Leakage Current | ILX | $V_{L X}=13 \mathrm{~V}$ |  |  | 0.01 | 20 | $\mu \mathrm{A}$ |
| LX Current Limit | ILIM |  |  | 1.6 | 2.1 | 2.8 | A |
| LX RMS Current Rating |  | Not tested |  |  |  | 1.4 | A |
| Soft-Start Period | tss |  |  | $\begin{aligned} & 4096 / \\ & \text { fosc } \end{aligned}$ |  |  | S |
| Soft-Start Step Size |  |  |  |  | $V_{\text {REF }} / 32$ |  | V |
| POSITIVE LINEAR-REGULATOR CONTROLLER |  |  |  |  |  |  |  |
| FBP Regulation Voltage | $V_{\text {FBP }}$ | IDRVP $=0.2 \mathrm{~mA}$ |  | 1.213 | 1.25 | 1.288 | V |
| FBP Fault Trip Level |  | $V_{\text {FBP }}$ falling |  | 0.96 | 1.0 | 1.04 | V |
| FBP Input Bias Current | IFBP | $\mathrm{V}_{\text {FBP }}=1.25 \mathrm{~V}$ |  | -50 |  | +50 | nA |
| FBP Effective Transconductance |  | $V_{\text {DRVP }}=10 \mathrm{~V}, \mathrm{I}$ DRVP $=0.1 \mathrm{~mA}$ to 2 mA |  | 75 |  |  | mS |

## Triple-Output TFT LCD Power Supply with Fault Protection

## ELECTRICAL CHARACTERISTICS (continued)

$\left(V_{I N}=3 V, \overline{S H D N}=I N, C_{R E F}=0.22 \mu F, P G N D=G N D, T_{A}=\mathbf{0}^{\circ} \mathbf{C}\right.$ to $+85^{\circ} \mathrm{C}$. Typical values are at $\mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$, unless otherwise noted. )

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| FBP Line Regulation |  | IDRVP $=0.2 \mathrm{~mA}, \mathrm{~V}$ IN $=2.7 \mathrm{~V}$ to 5.5 V |  | 1 |  | mV |
| Bandwidth |  | (Note 3) | 200 |  |  | kHz |
| DRVP Sink Current | IDRVP | $\mathrm{V}_{\mathrm{FBP}}=1.1 \mathrm{~V}, \mathrm{~V}_{\text {DRVP }}=10 \mathrm{~V}$ | 5 |  |  | mA |
| DRVP Off-Leakage Current |  | $\mathrm{V}_{\text {FBP }}=1.1 \mathrm{~V}, \mathrm{~V}_{\text {DRVP }}=28 \mathrm{~V}$ |  | 0.1 | 10 | $\mu \mathrm{A}$ |


| FBN Regulation Voltage | $V_{\text {FBN }}$ | IDRVN $=0.2 \mathrm{~mA}$ | 95 | 125 | 155 | mV |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| FBN Fault Trip Level |  | $V_{\text {FBN }}$ rising | 325 | 400 | 475 | mV |
| FBN Input Bias Current | IFBN | $\mathrm{V}_{\text {FBN }}=0 \mathrm{~V}$ | -50 |  | +50 | nA |
| FBN Effective Transconductance |  | $\mathrm{V}_{\text {DRVN }}=-10 \mathrm{~V}, \mathrm{IDRVN}=0.1 \mathrm{~mA}$ to 2 mA | 75 |  |  | mS |
| FBN Line Regulation |  | IDRVN $=0.2 \mathrm{~mA}, \mathrm{~V}$ IN $=2.7 \mathrm{~V}$ to 5.5 V |  | 1 |  | mV |
| Bandwidth |  | (Note 2) | 200 |  |  | kHz |
| DRVN Sink Current | IDRVN | $\mathrm{V}_{\text {FBN }}=200 \mathrm{mV}, \mathrm{V}_{\text {DRVN }}=-10 \mathrm{~V}$ | 5 |  |  | mA |
| DRVN Off-Leakage Current |  | $V_{\text {FBP }}=-0.1 \mathrm{~V}, \mathrm{~V}_{\text {DRVN }}=-20 \mathrm{~V}$ |  | 0.1 | 10 | $\mu \mathrm{A}$ |

LOGIC SIGNAL ( $\overline{\text { SHDN }}$ )

| Input Low Voltage |  | 100 mV typical hysteresis, V IN $=2.7 \mathrm{~V}$ to 5.5 V | 0.4 |  | V |
| :--- | :---: | :--- | :--- | :---: | :---: |
| Input High Voltage |  | V IN $=2.7 \mathrm{~V}$ to 5.5 V | 1.6 | V |  |
| Input Current | $\mathrm{I} \overline{\mathrm{SHDN}}$ |  | 0.01 | 1 | $\mu \mathrm{~A}$ |

LOGIC SIGNAL (FREQ)

| Input Low Voltage |  | $0.15 \times \mathrm{V}_{\text {IN }}$ typical hysteresis | $\begin{aligned} & 0.3 x \\ & \mathrm{~V}_{\text {IN }} \end{aligned}$ |  | V |
| :---: | :---: | :---: | :---: | :---: | :---: |
| Input High Voltage |  |  | $\begin{gathered} 0.7 x \\ V_{\text {IN }} \end{gathered}$ |  | V |
| Input Current | IfrREQ |  | 0.01 | 1 | $\mu \mathrm{A}$ |

## OVERCURRENT COMPARATOR

| Input Offset Voltage |  |  | -5 | +5 | mV |
| :--- | :--- | :--- | :--- | :---: | :---: |
| Input Bias Current | IOCN, <br> IOCP | VOCN $=V_{\text {OCP }}=V_{\text {IN }}$ | -50 | +50 | nA |
| OCN, OCP Input <br> Common-Mode Range |  |  | 1.5 | $0.8 \times$ <br> $V_{I N}$ | V |

FAULT TIMER AND GATE DRIVER

| Fault Timer Period | tfaULT | $V_{\text {FREQ }}=0 \mathrm{~V}, 32768 / \mathrm{fosc}$ |  | 64 |  | ms |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | $\mathrm{V}_{\text {FREQ }}=\mathrm{V}_{\text {IN }}$, 65536/fosC | 64 |  |  |  |
| GATE Output Sink Current During Slew | IGATE | $\mathrm{V}_{\mathrm{GATE}}=1.5 \mathrm{~V}$, during turn-on transition | 6 | 12 | 18 | $\mu \mathrm{A}$ |
| GATE Output Pulldown Resistance |  | $V_{\text {GATE }}<0.5 \mathrm{~V}$ |  |  | 200 | $\Omega$ |
| GATE Output Pullup Resistance |  |  |  |  | 200 | $\Omega$ |

## Triple-Output TFT LCD Power Supply with Fault Protection

ELECTRICAL CHARACTERISTICS


| PARAMETER | SYMBOL | CONDITIONS | MIN | MAX | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: |
| IN Supply Range | VIN |  | 2.7 | 5.5 | V |
| IN ULVO Threshold | VUVLO | VIN rising | 2.55 | 2.85 | V |
|  |  | VIN falling | 2.2 | 2.5 |  |
| IN Quiescent Current | IIN | $\mathrm{V}_{\mathrm{FB}}=\mathrm{V}_{\mathrm{FBP}}=1.5 \mathrm{~V}, \mathrm{~V}_{\text {FBN }}=0 \mathrm{~V}$ ( Note 1) |  | 1.0 | mA |
| IN Shutdown Current |  | $V \overline{\text { SHDN }}=0, \mathrm{VIN}=5 \mathrm{~V}$ |  | 1.0 | $\mu \mathrm{A}$ |
| REF Output Voltage | VREF | $-2 \mu \mathrm{~A}<\mathrm{I}_{\text {REF }}<50 \mu \mathrm{~A}$ | 1.231 | 1.269 | V |
| MAIN STEP-UP REGULATOR |  |  |  |  |  |
| Main Output Voltage Range | VMAIN |  | VIN | 13 | V |
| Operating Frequency | fosc | $\mathrm{V}_{\text {FREQ }}=\mathrm{V}_{\text {IN }}$ | 0.75 | 1.25 | MHz |
| Oscillator Maximum Duty Cycle |  |  | 78 | 92 | \% |
| FB Regulation Voltage | $V_{\text {FB }}$ | ILX = 200mA, slope $=0$ ( Note 2) | 1.215 | 1.260 | V |
| FB Fault Trip Level |  | $V_{\text {FB }}$ falling | 0.96 | 1.04 | V |
| Line Regulation |  | $\mathrm{V}_{\text {IN }}=2.7 \mathrm{~V}$ to 5.5 V |  | 0.45 | \%/V |
| FB Input Bias Current | IFB | $\mathrm{V}_{\mathrm{FB}}=1.5 \mathrm{~V}$ | -100 | +100 | nA |
| LX Switch On-Resistance | RLX(ON) |  |  | 450 | $\mathrm{m} \Omega$ |
| LX Current Limit | ILIM |  | 1.6 | 2.8 | A |
| POSITIVE LINEAR-REGULATOR CONTROLLER |  |  |  |  |  |
| FBP Regulation Voltage | VFBP | IDRVP $=0.2 \mathrm{~mA}$ | 1.213 | 1.288 | V |
| FBP Fault Trip Level |  | $V_{\text {FBP }}$ falling | 0.96 | 1.04 | V |
| FBP Input Bias Current | IFBP | $V_{\text {FBP }}=1.25 \mathrm{~V}$ | -50 | +50 | nA |
| FBP Effective Transconductance |  | $V_{\text {DRVP }}=10 \mathrm{~V}$, IDRVP $=0.1 \mathrm{~mA}$ to 2 mA | 60 |  | mS |
| Bandwidth |  | (Note 2) | 200 |  | kHz |
| DRVP Sink Current | IDRVP | $\mathrm{V}_{\mathrm{FBP}}=1.1 \mathrm{~V}, \mathrm{~V}_{\text {DRVP }}=10 \mathrm{~V}$ | 5 |  | mA |
| NEGATIVE LINEAR-REGULATOR CONTROLLER |  |  |  |  |  |
| FBN Regulation Voltage | VFBN | IDRVN $=0.2 \mathrm{~mA}$ | 95 | 155 | mV |
| FBN Fault Trip Level |  | $V_{\text {FBN }}$ rising | 325 | 475 | mV |
| FBN Input Bias Current | IfBN | $\mathrm{V}_{\text {FBN }}=0 \mathrm{~V}$ | -50 | +50 | nA |
| FBN Effective Transconductance |  | $\mathrm{V}_{\text {DRVN }}=-10 \mathrm{~V}, \mathrm{IDRVN}=0.1 \mathrm{~mA}$ to 2 mA | 60 |  | mS |
| Bandwidth |  | (Note 2) | 200 |  | kHz |
| DRVN Sink Current | IDRVN | $V_{\text {FBN }}=200 \mathrm{mV}, \mathrm{V}_{\text {DRVN }}=-10 \mathrm{~V}$ | 5 |  | mA |
| LOGIC SIGNAL ( $\overline{\text { SHDN }}$ ) |  |  |  |  |  |
| Input Low Voltage |  | 100mV typical hysteresis |  | 0.4 | V |
| Input High Voltage |  |  | 1.6 |  | V |
| Input Current | ISHDN |  |  | 1 | $\mu \mathrm{A}$ |

# Triple-Output TFT LCD Power Supply with Fault Protection 

## ELECTRICAL CHARACTERISTICS (continued)



| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| LOGIC SIGNAL (FREQ) |  |  |  |  |  |  |
| Input Low Voltage |  | $0.15 \times \mathrm{V}$ IN typical hysteresis |  |  | $0.3 \times \mathrm{V}_{\text {IN }}$ | V |
| Input High Voltage |  |  | $0.7 \times \mathrm{V}$ IN |  |  | V |
| Input Current | IFREQ |  |  |  | 1 | $\mu \mathrm{A}$ |
| OVERCURRENT COMPARATOR |  |  |  |  |  |  |
| Input Offset Voltage |  |  | -5 |  | +5 | mV |
| Input Bias Current | $\begin{aligned} & \text { IoCN, } \\ & \text { IOCP } \end{aligned}$ | $\mathrm{V}_{\text {OCN }}=\mathrm{V}_{\text {OCP }}=\mathrm{V}_{\text {IN }}$ | -50 |  | +50 | nA |
| OCN, OCP Input Common-Mode Range |  |  | 1.5 |  | $\begin{gathered} 0.8 x \\ V_{\text {IN }} \end{gathered}$ | V |
| FAULT TIMER AND GATE DRIVER |  |  |  |  |  |  |
| GATE Output Sink Current | IGATE | $\mathrm{V}_{\mathrm{GATE}}=1.5 \mathrm{~V}$, during turn-on transition | 6 |  | 18 | $\mu \mathrm{A}$ |
| GATE Output Pulldown Resistance |  | $V_{\text {GATE }}<0.5 \mathrm{~V}$ |  |  | 200 | $\Omega$ |
| GATE Output Pullup Resistance |  |  |  |  | 200 | $\Omega$ |

Note 1: Quiescent current does not include switching losses.
Note 2: FB regulation voltage is tested with no slope compensation ramp. Slope compensation needs to be included when selecting resisitors for setting the output voltage (see Main Step-Up Regulator and Output Voltage Selection sections).
Note 3: Guaranteed by design. Not production tested.
Note 4: Specifications to $-40^{\circ} \mathrm{C}$ are guaranteed by design, not production tested.

Typical Operating Characteristics
(Circuit of Figure 1, $\mathrm{V}_{\mathrm{IN}}=+3.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{MAIN}}=+9 \mathrm{~V}, \mathrm{~V}_{\mathrm{PL}}=+20 \mathrm{~V}, \mathrm{~V}_{\mathrm{NL}}=-7 \mathrm{~V}, \overline{\mathrm{SHDN}}=\mathrm{FREQ}=\mathrm{IN}, \mathrm{PGND}=\mathrm{GND}, \mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$, unless otherwise noted.)


## Triple-Output TFT LCD Power Supply with Fault Protection

(Circuit of Figure 1, $\mathrm{V}_{I N}=+3.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{MAIN}}=+9 \mathrm{~V}, \mathrm{~V}_{\mathrm{PL}}=+20 \mathrm{~V}, \mathrm{~V}_{\mathrm{NL}}=-7 \mathrm{~V}, \overline{\mathrm{SHDN}}=\mathrm{FREQ}=\mathrm{IN}, \mathrm{PGND}=\mathrm{GND}, \mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$, unless otherwise noted.)



STEP-UP REGULATOR LOAD-TRANSIENT RESPONSE (O TO 200mA)



A: $\mathrm{V}_{\mathrm{IN}}, 5 \mathrm{~V} / \mathrm{div}$
B: $\mathrm{V}_{\mathrm{GATE}}, 5 \mathrm{~V} / \mathrm{div}$
C: VC2, $5 \mathrm{~V} / \mathrm{div}$
D: $V_{\text {MAIN }}=9 \mathrm{~V}, 5 \mathrm{~V} / \mathrm{div}$

A: INDUCTOR CURRENT, 1A/div
B: $V_{\text {MAIN }}=9 \mathrm{~V}, 100 \mathrm{mV} /$ div, AC-COUPLED
C: $I_{\text {MAIN }}=0$ TO 1A, 1A/div


0


A: $\mathrm{V}_{\text {IN }}, 5 \mathrm{~V} / \mathrm{div}$
B: $V_{\text {GATE }}, 5 \mathrm{~V} / \mathrm{div}$
C: $\mathrm{V}_{\mathrm{C} 2}, 5 \mathrm{~V} / \mathrm{div}$
D: $\mathrm{V}_{\text {MAIN }}=9 \mathrm{~V}, 5 \mathrm{~V} / \mathrm{div}$

# Triple-Output TFT LCD Power Supply with Fault Protection 

Typical Operating Characteristics (continued)
(Circuit of Figure 1, $\mathrm{V}_{\mathrm{IN}}=+3.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{MAIN}}=+9 \mathrm{~V}, \mathrm{~V}_{\mathrm{PL}}=+20 \mathrm{~V}, \mathrm{~V}_{\mathrm{NL}}=-7 \mathrm{~V}, \overline{\mathrm{SHDN}}=\mathrm{FREQ}=\mathrm{IN}, \mathrm{PGND}=\mathrm{GND}, \mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$, unless otherwise noted.)


A: $\mathrm{V}_{\mathrm{IN}}, 5 \mathrm{~V} / \mathrm{div}$
B: $V_{\text {MAIN }}=9 \mathrm{~V}, 5 \mathrm{~V} / \mathrm{div}$
C: $\mathrm{V}_{\mathrm{PL}}=20 \mathrm{~V}, 10 \mathrm{~V} / \mathrm{div}$
$D: V_{N L}=-7 \mathrm{~V}, 10 \mathrm{~V} / \mathrm{div}$

POWER-UP SEQUENCE USING SHDN CONTROL


A: VSHDN, $5 V / d i v$
B: $\mathrm{V}_{\text {MAIN }}=9 \mathrm{~V}, 5 \mathrm{~V} /$ div
C: $V_{P L}=20 \mathrm{~V}, 10 \mathrm{~V} / \mathrm{div}$
D: $V_{N L}=-7 V, 10 V / d i v$


A: V $\overline{\text { SHDN }}, 5 \mathrm{~V} / \mathrm{div}$
B: VGATE, $5 \mathrm{~V} / \mathrm{div}$
C: $\mathrm{V}_{\mathrm{CL}}, 5 \mathrm{~V} / \mathrm{div}$
D: $\mathrm{V}_{\text {MAIN }}=9 \mathrm{~V}, 5 \mathrm{~V} / \mathrm{div}$

STEP-UP REGULATOR NORMAL OPERATION
(200mA LOAD)


A: $V_{L x}, 5 \mathrm{~V} /$ div
B: $\mathrm{V}_{\text {MAIN }}=9 \mathrm{~V}, 50 \mathrm{mV} / \mathrm{div}$, AC-COUPLED
C: INDUCTOR CURRENT, $500 \mathrm{~mA} / \mathrm{div}$


A: VSHDN, $5 \mathrm{~V} / \mathrm{div}$
B: VGATE, $5 \mathrm{~V} / \mathrm{div}$
C: $\mathrm{V}_{\mathrm{C} 2}, 5 \mathrm{~V} / \mathrm{div}$
D: $V_{\text {MAIN }}=9 \mathrm{~V}, 5 \mathrm{~V} / \mathrm{div}$

POSITIVE CHARGE-PUMP OUTPUT VOLTAGE vs. LOAD CURRENT


LOAD CURRENT (mA)

## Triple-Output TFT LCD Power Supply with Fault Protection

Typical Operating Characteristics (continued)
(Circuit of Figure 1, $\mathrm{V}_{\mathrm{IN}}=+3.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{MAIN}}=+9 \mathrm{~V}, \mathrm{~V}_{\mathrm{PL}}=+20 \mathrm{~V}, \mathrm{~V}_{\mathrm{NL}}=-7 \mathrm{~V}, \overline{\mathrm{SHDN}}=\mathrm{FREQ}=\mathrm{IN}, \mathrm{PGND}=\mathrm{GND}, \mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$, unless otherwise noted.)



NEGATIVE CHARGE-PUMP
OUTPUT VOLTAGE vs. LOAD CURRENT


OAD CURRENT (mA)

$A: V_{P L}=20 \mathrm{~V}, 50 \mathrm{mV} / \mathrm{div}, \mathrm{AC}-\mathrm{COUPLED}$ B: $\mathrm{IpL}=0 \mathrm{TO} 10 \mathrm{~mA}, 10 \mathrm{~mA} /$ div



LOAD CURRENT (mA)

# Triple-Output TFT LCD Power Supply with Fault Protection 

Typical Operating Characteristics (continued)
(Circuit of Figure 1, $\mathrm{V}_{\mathrm{IN}}=+3.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{MAIN}}=+9 \mathrm{~V}, \mathrm{~V}_{\mathrm{PL}}=+20 \mathrm{~V}, \mathrm{~V}_{\mathrm{NL}}=-7 \mathrm{~V}, \overline{\mathrm{SHDN}}=\mathrm{FREQ}=\mathrm{IN}, \mathrm{PGND}=\mathrm{GND}, \mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$, unless otherwise noted.)

$400 \mu \mathrm{~s} / \mathrm{div}$
$\mathrm{A}: \mathrm{V}_{\mathrm{NL}}=-7 \mathrm{~V}, 50 \mathrm{mV} / \mathrm{div}, \mathrm{AC}-C O U P L E D$
B: $I_{\mathrm{NL}}=0$ TO $-10 \mathrm{~mA}, 10 \mathrm{~mA} / \mathrm{div}$


20ms/div
A: $V_{\text {Gate, }}$, $\mathrm{V} / \mathrm{div}$
B: $\mathrm{V}_{\text {MAIN }}, 5 \mathrm{~V} / \mathrm{div} ; \mathrm{I}_{\text {MAIN }}=1.5 \mathrm{~A}$
C: $V_{\text {PL }}, 10 \mathrm{~V} / \mathrm{div} ; ~ l_{\mathrm{PL}}=10 \mathrm{~mA}$
$D: V_{N L}, 10 \mathrm{~V} / \mathrm{div} ; I_{N L}=10 \mathrm{~mA}$

OVERCURRENT PROTECTION RESPONSE TO OVERLOAD DURING NORMAL OPERATION


A: $\mathrm{V}_{\text {GATE, }} 5 \mathrm{~V} / \mathrm{div}$
B: $V_{\text {MAIN }}=9 \mathrm{~V}, 5 \mathrm{~V} / \mathrm{div} ; I_{\text {MAIN }}=200 \mathrm{~mA}$ T0 1.5A
$C: V_{P L}=20 \mathrm{~V}, 10 \mathrm{~V} / \mathrm{div} ; \mathrm{IPL}^{2}=10 \mathrm{~mA}$
$D: V_{N L}=-7 V, 10 \mathrm{~V} / \mathrm{div} ; I_{\mathrm{NL}}=10 \mathrm{~mA}$



Triple-Output TFT LCD Power Supply with Fault Protection

Pin Description

| PIN | NAME | FUNCTION |
| :---: | :---: | :---: |
| 1 | $\overline{\text { SHDN }}$ | Active-Low Shutdown Control Input. Pull $\overline{\text { SHDN }}$ below the 0.4 V logic-low level to turn off all sections of the device and pull the GATE pin high. Pull $\overline{\text { SHDN }}$ above the 1.6 V logic-high level to enable the device. Do not leave $\overline{\text { SHDN floating. }}$ |
| 2 | PGND | Power Ground. PGND is the source of the N-channel power MOSFET. Connect PGND to the analog ground (GND) at the device's pins. |
| 3 | GND | Analog Ground. Connect GND to the power ground (PGND) at the device's pins. |
| 4 | REF | Internal Reference Bypass Terminal. Connect a $0.22 \mu \mathrm{~F}$ ceramic capacitor from REF to the analog ground (GND). External load capability is at least $50 \mu \mathrm{~A}$. |
| 5 | FB | Main Step-Up Regulator Feedback Input. FB regulates to 1.25 V nominal. Connect FB to the center of a resistive voltage-divider between the main output (VMAIN) and the analog ground (GND) to set the main step-up regulator output voltage. Place the resistive voltage-divider close to the pin. |
| 6 | FBN | Negative Linear-Regulator Feedback Input. FBN regulates to 125 mV nominal. Connect FBN to the center of a resistive voltage-divider between the negative output ( $\mathrm{V}_{\text {NEG }}$ ) and the REF to set the negative linear-regulator output voltage. Place the resistive voltage-divider close to the pin. |
| 7 | DRVN | Negative Linear-Regulator Base Drive. Open drain of an internal P-channel MOSFET. Connect DRVN to the base of the external linear-regulator NPN pass transistor (see Pass Transistor Selection section). |
| 8 | DRVP | Positive Linear-Regulator Base Drive. Open drain of an internal N -channel MOSFET. Connect DRVP to the base of the external linear-regulator PNP pass transistor (see Pass Transistor Selection section). |
| 9 | FBP | Positive Linear-Regulator Feedback Input. FBP regulates to 1.25 V nominal. Connect FBP to the center of a resistive voltage-divider between the positive output (VPOS) and the analog ground (GND) to set the positive linear-regulator output voltage. Place the resistive voltage-divider close to the pin. |
| 10 | FREQ | Frequency Select Input. Pull FREQ above logic-high level $\left(0.7 \times \mathrm{V}_{\text {IN }}\right)$ to set the frequency to 1 MHz and pull FREQ below logic-low level $\left(0.3 \times \mathrm{V}_{\mathrm{IN}}\right)$ to set the frequency to 500 kHz . Do not leave FREQ floating. |
| 11 | LX | Switching Node. Drain of the internal N-channel power MOSFET for the main step-up regulator. |
| 12 | TGND | Internal connection. Connect this pin to ground. |
| 13 | OCN | Overcurrent Comparator Inverting Input. OCN connects to the center tap of a resistive voltagedivider connected to the drain of the input protection P-channel MOSFET (see the Input Overcurrent Protection section). If unused, connect OCN to REF. |
| 14 | OCP | Overcurrent Comparator Noninverting Input. OCP is connected to the center tap of a resistive voltage-divider that sets the input overcurrent threshold (see the Input Overcurrent Protection section). If unused, connect OCP to GND. |
| 15 | GATE | Gate Driver Output to the External P-Channel MOSFET (see the Input Overcurrent Protection section). If unused, leave GATE open. |
| 16 | IN | Supply Input. The supply voltage powers all the control circuitry. The input voltage range is from 2.7 V to 5.5 V . Bypass with a $0.1 \mu \mathrm{~F}$ ceramic capacitor between IN and GND, as close to the pins as possible. |

## Triple-Output TFT LCD Power Supply with Fault Protection



Figure 1. Standard Application Circuit

## Triple-Output TFT LCD Power Supply with Fault Protection



Figure 2. MAX1889 System Functional Diagram

# Triple-Output TFT LCD Power Supply with Fault Protection 

Table 1. Component List

| DESIGNATION | DESCRIPTION |
| :---: | :---: |
| C2, C3 | 3.3 $\mu \mathrm{F}, 6.3 \mathrm{~V}$ X5R ceramic capacitors (0805) Taiyo Yuden JMK212BJ335MG |
| C4, C5, C6 | 4.7 FF, 10V X7R ceramic capacitors (1210) Taiyo Yuden LMK352BJ475MF |
| D1 | 1.0A, 30V Schottky diode (S-flat) Toshiba CRSO2 |
| D2, D3, D4 | 200mA, 25V dual-series Schottky diodes (SOT23) <br> Fairchild BAT54S |
| D5 | 250mA, 75 V switching diode (SOT23) Central Semiconductor CMPD914 |
| L1 | $6.8 \mu \mathrm{H}, 1.3 \mathrm{~A}$ inductor Coilcraft LPO2506IB-682 |
| P1 | 2.4A, 20V P-channel MOSFET (3-pin SuperSOT) Fairchild FDN304P |
| Q1 | 200mA, 40V NPN bipolar transistor (SOT23) Fairchild MMBT3904 |
| Q2 | 200mA, 40V PNP bipolar transistor (SOT23) Fairchild MMBT3906 |

## Standard Application Circuit

The standard application circuit (Figure 1) of the MAX1889 generates $+9 \mathrm{~V},+20 \mathrm{~V}$, and -7 V outputs for TFT LCD displays. The input voltage is from 2.7 V to 5.5 V . Table 1 lists the recommended component options and Table 2 lists the component suppliers.

## Detailed Description

The MAX1889 contains a high-performance, step-up switching regulator, two low-cost linear-regulator controllers, and multiple levels of protection circuitry. Figure 2 shows the system functional diagram of the device. The output voltage of the main step-up converter (VMAIN) can be set from VIN to 13 V with an external resistive volt-age-divider. The high switching frequency $(500 \mathrm{kH} / 1 \mathrm{MHz})$ of the main step-up converter and current-mode control provide fast transient response and allow the use of lowprofile inductors and ceramic capacitors. The internal power MOSFET minimizes the external component count while achieving high efficiency by incorporating a lossless current-sensing technology.
The switching node (LX) can generate both positive and negative voltage supplies by driving charge-pump stages of capacitors and diodes. The user can use as many charge-pump stages as needed to generate supply voltages of more than +30 V and -15 V . The positive and negative linear-regulator controllers postregulate the charge-pump supply voltages and allow users to program power-up sequencing as well.
The unique input switch control of the MAX1889 senses the current drawn from the input power supply by monitoring the voltage drop across the input P-channel MOSFET and latches off if an overcurrent condition lasts for more than the fault timer period. In addition, all three outputs are monitored for fault conditions that last longer than the fault latch timer. If the junction temperature of the IC exceeds $+160^{\circ} \mathrm{C}$, the device goes into a latched shutdown state.

## Main Step-Up Regulator

 The main step-up regulator switches at 1 MHz (or 500 kHz ) and employs a current-mode control architecture to maximize loop bandwidth to provide fast-transient response to pulsed loads found in source drivers for TFT LCD panels. Also, the high switching frequency allows the use of low-profile inductors and capacitors to minimize the thickness of LCD panel designs. The integrated high-efficiency MOSFET and the IC's built-in soft-start function reduce the number of external components required while controlling inrush current.
## Table 2. Component Suppliers

| SUPPLIER | PHONE | FAX | WEBSITE |
| :--- | :---: | :---: | :--- |
| Coilcraft | $847-639-6400$ | $847-639-1469$ | www.coilcraft.com |
| Fairchild | $408-822-2000$ | $408-822-2102$ | www.fairchildsemi.com |
| Taiyo Yuden | $800-348-2496$ | $847-925-0899$ | www.t-yuden.com |
| Toshiba | $949-455-2000$ | $949-859-3963$ | www.toshiba.com |

## Triple-Output TFT LCD Power Supply with Fault Protection

Depending on the input-to-output voltage ratio, the regulator controls the output voltage and the power delivered to the output by modulating the duty cycle (D) of the power MOSFET in each switching cycle. The duty cycle of the MOSFET is approximated by:

$$
D \approx \frac{V_{\text {MAIN }}-V_{I N}}{V_{\text {MAIN }}}
$$

On the rising edge of the internal clock, the controller sets a flip-flop, which turns on the N-channel MOSFET (Figure 3). The input voltage is applied across the
inductor. The inductor current ramps up linearly, storing energy in a magnetic field. Once the sum of the feedback voltage error-amplifier output, slope-compensation, and current-feedback signals trip the multi-input PWM comparator, the MOSFET turns off, and the flipflop resets. Since the inductor current is continuous, a transverse potential develops across the inductor that turns on the diode (D1). The voltage across the inductor becomes the difference between the output voltage and the input voltage. This discharge condition forces the current through the inductor to ramp back down, transferring the energy to the output capacitor and the load. The MOSFET remains off for the rest of the clock cycle.


Figure 3. Main Step-Up Regulator Functional Diagram

# Triple-Output TFT LCD Power Supply with Fault Protection 

## Positive Linear-Regulator Controller

The positive linear regulator provides the positive high voltage for the TFT LCD gate drivers. The high voltage can be produced using a charge-pump circuit as shown in Figure 1. Use as many stages as necessary to obtain the required output voltage (see the Selecting the Number of Charge-Pump Stages section). The positive linear-regulator controller is an analog gain block with an open-drain N-channel output. It drives an external PNP pass transistor with a $3 \mathrm{k} \Omega$ base-to-emitter resistor to post-regulate the charge-pump output (Figure 1). The regulator controller is designed to be stable with an output capacitor of $0.1 \mu \mathrm{~F}$ or more.
To enable the regulator using an external control signal, apply the logic-control input in series with a signal diode (Figure 1). Additional delay can be added with external circuitry.
Note that the voltage rating of the DRVP output is 28 V . If higher voltages are present, an external cascode NPN transistor should be used with the emitter connected to DRVP, the base to $\mathrm{V}_{\text {MAIN }}$, and the collector to the base of the PNP.

## Negative Linear-Regulator Controller

The negative linear regulator provides the negative voltage required to supply gate drivers in TFT LCD panels. The negative voltage can be produced using a charge pump circuit as shown in Figure 1. Use as many stages as necessary to obtain the required output voltage (see the Selecting the Number of Charge-Pump Stages section). The negative linear-regulator controller is an analog gain block with an open-drain P-channel output. It drives an external NPN pass transistor with a $3 k \Omega$ base-to-emitter resistor to postregulate the charge-pump out-


Figure 4. External Input P-Channel MOSFET Switch Control
put (Figure 1). The regulator controller is designed to be stable with an output capacitor of $0.1 \mu \mathrm{~F}$ or more.
The negative linear regulator is enabled as soon as the main step-up regulator is enabled. To enable the regulator using an external control signal, apply the logic-control input through an open-drain output or an N -channel MOSFET (Figure 1). Additional delay can be added with external circuitry (see the Applications Information section).
Note that the voltage rating of the DRVN output is VIN -28 V . If higher voltages are present, an external cascode PNP transistor should be used with the emitter connected to DRVN, the base to GND, and the collector to the base of the NPN.

## Undervoltage Lockout (UVLO)

 The UVLO comparator of the MAX1889 compares the input voltage at the IN pin with the UVLO threshold (2.7V rising, 2.35 V falling, typ) to ensure that the input voltage is high enough for reliable operation. The 350 mV (typ) hysteresis prevents supply transients from causing a restart. Once the input voltage exceeds the UVLO threshold, the controller enables the reference block. Once the reference is above 1.05 V , an internal $12 \mu \mathrm{~A}$ current source pulls the GATE pin low and turns on an external P-channel MOSFET switch (P1, Figure 1) that connects the input supply to the regulator. When the input voltage falls below the UVLO threshold, the controller sets the fault latch and pulls GATE high with an internal $100 \Omega$ switch to turn off P1 quickly (Figure 4).Reference Voltage (REF)
The reference output is nominally 1.25 V , and can source at least $50 \mu \mathrm{~A}$ (see the Typical Operating Characteristics). Bypass REF with a $0.22 \mu \mathrm{~F}$ ceramic capacitor connected between REF and GND.

Oscillator Frequency (FREQ) The internal oscillator frequency is pin programmable. Connect FREQ to ground for 500 kHz operation and to VIN for 1 MHz operation. Note that the soft-start period scales with the oscillator frequency (see the Soft-Start section).

## Shutdown (SHDN)

A logic-low signal on the $\overline{\text { SHDN }}$ pin disables all device functions including the reference. When shut down, the supply current drops to $0.1 \mu \mathrm{~A}(\mathrm{typ})$ to maximize battery life. The output capacitance, feedback resistors, and load current determine the rate at which each output voltage decays. A logic-high signal on the SHDN pin activates the MAX1889 (see the Power-Up Sequencing section). Do not leave the pin floating. If unused, connect $\overline{S H D N}$ to $I N$. Toggling SHDN or cycling IN clears the fault latch.

# Triple-Output TFT LCD Power Supply with Fault Protection 

## Power-Up Sequencing and Inrush Current Control

Once $\overline{\text { SHDN }}$ is high, the MAX1889 enables the UVLO circuitry and compares the input voltage with the UVLO rising threshold ( $2.7 \mathrm{~V}, \mathrm{typ}$ ). If the input voltage exceeds the UVLO rising threshold, the reference is enabled. When the reference voltage ramps up above 1.05 V (typ), the MAX1889 enables the oscillator and turns on the external P-channel MOSFET P1 (Figure 1) by pulling GATE low. GATE is pulled down with a $12 \mu \mathrm{~A}$ current source. Add a capacitor from the gate of P1 to its drain to slow down the turn-on rate of the MOSFET, and reduce inrush current. Once GATE reaches around 0.6 V , an internal N -channel MOSFET turns on and pulls GATE to ground in order to maximize the enhancement of the external P-channel MOSFET. As P1 fully turns on, the main step-up regulator powers up with soft-start (see the Soft-Start section). The negative linear regulator is enabled at the same time as the main step-up regulator. The positive linear regulator is enabled after the soft-start routine is completed. The fault detection timer begins after the main step-up regulator has finished its soft-start period.

## Soft-Start

 The soft-start of the main step-up regulator (Figure 3) is achieved by ramping up the reference voltage of the multi-input PWM comparator in 4096 oscillator clock cycles. The 4096 clock cycles correspond to 4.096 ms for 1 MHz operation and 8.192 ms for 500 kHz operation. The reference of the PWM comparator comes from a 5 -bit DAC that generates 32 steps when the reference ramps up from OV to its final value. This soft-start method allows a gradual increase of the output voltage to reduce the input surge current (see the startup waveforms in the Typical Operating Characteristics). The average input current is given as:$$
I_{I_{N} A V G}=\frac{V_{\text {MAIN }}{ }^{2} \times C_{O U T}}{V_{\text {IN }} \times \mathrm{t}_{\mathrm{SS}} \times \eta}
$$

where $V_{\text {MAIN }}$ is the main step-up regulator output voltage, $\mathrm{V}_{\mathrm{IN}}$ is the input voltage, Cout is the main step-up regulator output capacitor, $\eta$ is the efficiency of the step-up regulator, and tss is the soft-start period (4.096ms for 1 MHz operation and 8.192 ms for 500 kHz operation).

## Input Overcurrent Protection

The high-side overcurrent comparator of the MAX1889 provides input overcurrent protection when it is used together with the external P-channel MOSFET switch P1 (Figure 1). Connect resistive voltage-dividers from the source and drain of P1 to GND to set the overcurrent threshold. The center taps of the dividers are connected to the overcurrent comparator inputs (OCN and OCP) See the Setting the Input Overcurrent Threshold section for information on calculating resistor values. An overcurrent event activates the fault-protection circuitry.

## Fault Protection

Once the soft-start routine is completed, if the output of the main regulator or either linear regulator is below its respective fault-detection threshold, or the input overcurrent comparator pulls high, the MAX1889 activates the fault timer. If the fault condition still exists after the 64ms fault-timer duration, the MAX1889 sets the fault latch, which shuts down all the outputs except the reference, which remains active. After removing the fault condition, toggle $\overline{\text { SHDN }}$ (below 0.4 V ) or cycle the input voltage (below 2.2V) to clear the fault latch and reactivate the device.

## Thermal Shutdown

The thermal shutdown feature limits total power dissipation in the MAX1889. When the junction temperature ( T ) exceeds $+160^{\circ} \mathrm{C}$, a thermal sensor sets the fault latch (Figure 2), which shuts down all the outputs except the reference, allowing the device to cool down. Once the device cools down by $15^{\circ} \mathrm{C}$, toggle $\overline{\mathrm{SHDN}}$ (below 0.4 V ) or cycle the input voltage (below 2.2 V ) to clear the fault latch and reactivate the device.

## Design Procedure

## Main Step-Up Regulator

Output Voltage Selection
Adjust the output voltage by connecting a resistive volt-age-divider from the output ( $\mathrm{V}_{\text {MAIN }}$ ) to GND with the center tap connected to FB (Figure 1). Select R7 in the $10 \mathrm{k} \Omega$ to $50 \mathrm{k} \Omega$ range. Calculate R6 with the following equations:

$$
\mathrm{R} 6=\mathrm{R} 7\left[\left(\mathrm{~V}_{\mathrm{MAIN}} / \mathrm{V}_{\mathrm{FB}}\right)-1\right]
$$

where

$$
V_{F B}=1.242 \mathrm{~V}-(\mathrm{D} \times 20 \mathrm{mV}) \text { and } \mathrm{D} \approx \frac{\mathrm{~V}_{\text {MAIN }}-\mathrm{V}_{\mathrm{IN}}}{\mathrm{~V}_{\text {MAIN }}}
$$

For example, at $\mathrm{V}_{\mathrm{IN}}=3 \mathrm{~V}, \mathrm{~V}_{\mathrm{MAIN}}=9 \mathrm{~V}, \mathrm{D} \approx 0.66$, and $\mathrm{V}_{\mathrm{FB}}$ $=1.229 \mathrm{~V}$.
$\mathrm{V}_{\text {MAIN }}$ can range from $\mathrm{V}_{\mathrm{IN}}$ to 13 V .

# Triple-Output TFT LCD Power Supply with Fault Protection 

## Inductor Selection

The minimum inductance value, peak current rating, series resistance, and size are factors to consider when selecting the inductor. These factors influence the converter's efficiency, maximum output load capability, transient response time, and output voltage ripple. For most applications, values between $3.3 \mu \mathrm{H}$ and $20 \mu \mathrm{H}$ work best with the MAX1889's switching frequencies.
The maximum load current, input voltage, output voltage, and switching frequency determine the inductor value. For a given load current, higher inductor value results in lower peak current and, thus, less output ripple, but degrades the transient response and possibly increases the size of the inductor. The equations provided here include a constant defined as LIR, which is the ratio of the peak-to-peak inductor current ripple to the average DC inductor current. For a good compromise between the size of the inductor, power loss, and output voltage ripple, select an LIR of 0.3 to 0.5 . The inductance value is then given by:

$$
L=\left(\frac{V_{\text {IN(TYP) }}}{V_{\text {MAIN }}}\right)^{2}\left(\frac{V_{\text {MAIN }}-V_{I N(T Y P)}}{I_{\text {MAIN(MAX) }{ }^{f} \mathrm{FSC}}}\right)\left(\frac{1}{\operatorname{LIR}}\right) \eta
$$

where $\eta$ is the efficiency, fosc is the oscillator frequency (see the Electrical Characteristics), and IMAIN includes the primary load current and the input supply currents for the charge pumps. Considering the typical application circuit, the maximum average DC load current ( $\operatorname{MMAIN}($ MAX $)$ ) is 200 mA with a 9 V output. Based on the above equations, and assuming 85\% efficiency and a switching frequency of 1 MHz , the inductance value is $9.4 \mu \mathrm{H}$ for an LIR of 0.3. The inductance value is $5.6 \mu \mathrm{H}$ for an LIR of 0.5 . The inductance in the standard application circuit is chosen to be $6.8 \mu \mathrm{H}$.
The inductor's peak current rating should be higher than the peak inductor current throughout the normal operating range. The peak inductor current is given by:

$$
I_{\text {PEAK }}=\left(\frac{I_{\text {MAIN(MAX) }} V_{\text {MAIN }}}{V_{I N(M I N)}}\right)\left(1+\frac{\text { LIR }}{2}\right)\left(\frac{1}{\eta}\right)
$$

Under fault conditions, the inductor current can reach the internal LX current limit (see the Electrical Characteristics). However, soft saturation inductors and the controller's fast current-limit circuitry protect the device from failure during such a fault condition.
The inductor's DC resistance can significantly affect efficiency due to conduction losses in the inductor.

The power loss due to the inductor's series resistance (PLR) can be approximated by the following equation:

$$
P_{\mathrm{LR}}=\mathrm{I}_{(\mathrm{LAVG})} 2^{2} R_{\mathrm{L}} \cong\left(\frac{I_{\mathrm{MAIN}} \times V_{\mathrm{MAIN}}}{\mathrm{~V}_{\mathrm{IN}}}\right)^{2} R_{\mathrm{L}}
$$

where $I_{L(A V G)}$ is the average inductor current and $R_{L}$ is the inductor's series resistance. For best performance, select inductors with resistance less than the internal N-channel MOSFET's on-resistance ( $0.25 \Omega$ typ). To minimize radiated noise in sensitive applications, use a shielded inductor.

## Output Capacitor

The output capacitor affects the circuit stability and output voltage ripple. A $10 \mu \mathrm{~F}$ ceramic capacitor works well in most applications. Depending on the output capacitor chosen, feedback compensation may be required or desirable to increase the loop-phase margin or increase the loop bandwidth for transient response (see the Feedback Compensation section).
The total output voltage ripple has two components: the capacitive ripple caused by the charging and discharging of the output capacitance, and the ohm ripple due to the capacitor's equivalent series resistance (ESR):

$$
\begin{aligned}
& \mathrm{V}_{\text {RIPPLE }}=\mathrm{V}_{\text {RIPPLE(ESR }}+\mathrm{V}_{\text {RIPPLE }}(\mathrm{C}) \\
& V_{\text {RIPPLE(ESR) }} \approx{ }_{\text {PPEAK }} R_{\text {ESR(COUT) }} \text {, and } \\
& V_{\text {RIPPLE }(C)} \approx \frac{I_{\text {MAIN }}}{C_{\text {OUT }}}\left(\frac{V_{\text {MAIN }}-V_{\text {IN }}}{V_{\text {MAIN }}{ }^{\prime} \text { OSC }}\right)
\end{aligned}
$$

where IPEAK is the peak inductor current (see the Inductor Selection section). For ceramic capacitors, the output voltage ripple is typically dominated by $\mathrm{V}_{\text {RIPPLE }}(\mathrm{C})$. The voltage rating and temperature characteristics of the output capacitor must also be considered.

## Step-Up Regulator Compensation

The loop stability of a current-mode step-up regulator can be analyzed using a small-signal model. In continuous conduction mode (CCM), the loop-gain transfer function consists of a dominant pole, a high-frequency pole, a right-half-plane (RHP) zero, and an ESR zero. In the case of ceramic output capacitors, the ESR zero is at a very high frequency.

## Triple-Output TFT LCD Power Supply with Fault Protection

Therefore, the dominant pole and the RHP zero determine the loop response of the step-up regulator. The frequency of the dominant pole is:

$$
f_{P-D O M I N A N T}=\frac{1}{2 \pi R_{\mathrm{L}} \mathrm{C}}
$$

where $R L$ is the load resistance and $C$ is the output capacitor. The frequency of the RHP zero is:

$$
\mathrm{f}_{-} \mathrm{RHP}=(1-\mathrm{D})^{2} \frac{\mathrm{R}_{\mathrm{L}}}{2 \pi \mathrm{~L}}
$$

where $D$ is the duty cycle, $L$ is the inductance, and the DC gain is given by:

$$
A_{D C}=20 \log \left(\frac{R 1}{R 1+R 2} \times \frac{(1-D)}{R_{C S}} \times R_{L}\right)
$$

where Rcs is the internal current-sense resistor, and R1 and R2 are the feedback divider resistors in Figure 5.
However, adding lead or lag compensation (Figure 5) can be useful to adjust the trade-off between stability and transient response. If greater phase margin is needed for stability, and lower bandwidth is acceptable, add a pole-zero pair by connecting an RC network from the FB pin to ground (lag compensation). Conversely, if higher bandwidth is required for faster transient response, and lower phase margin is acceptable, add a


Figure 5. External Compensation
zero-pole pair to the loop by connecting an RC network from the FB pin to the main output (lead compensation).
The frequencies of the pole and zero for the lag compensation are:

$$
\begin{aligned}
& \mathrm{f}_{\mathrm{P}_{-} \mathrm{FB}}=\frac{1}{2 \pi\left(\mathrm{R} 4 \frac{\mathrm{R} 1 \times \mathrm{R} 2}{\mathrm{R} 1+\mathrm{R} 2}\right) \mathrm{C} 1} \\
& \mathrm{f}_{\mathrm{Z}_{-} \mathrm{FB}}=\frac{1}{2 \pi \mathrm{R} 4 \times \mathrm{C} 1}
\end{aligned}
$$

The frequencies of the zero and pole for the lead compensation are:

$$
\begin{aligned}
& \mathrm{f}_{\mathrm{Z}_{-} \mathrm{FF}}=\frac{1}{2 \pi(\mathrm{R} 2+\mathrm{R} 3) \times \mathrm{C} 2} \\
& \mathrm{f}_{\mathrm{P}_{-} \mathrm{FF}}=\frac{1}{2 \pi\left(\mathrm{R} 3+\frac{\mathrm{R} 1 \times \mathrm{R} 2}{\mathrm{R} 1+\mathrm{R} 2}\right) \mathrm{C} 2}
\end{aligned}
$$

The compensation resistors R3 and R4 change the AC gain affecting the loop bandwidth and phase margin at crossover. Reducing the bandwidth too much (FB compensation) harms the transient response, while increasing it too much harms phase margin and stability. As a rule, start with R3 (or R4) approximately equal to half of R1 (or R2). In a typical application, the compensation capacitors C1 and C2 can be in the range between 100 pF to 1000 pF . Then, check the stability by monitoring the transient response waveform when a pulsed load is applied to the output.

## Using Compensation for Improved Soft-Start

The digital soft-start of the main step-up regulator limits the average input current during startup. In order to smooth out each step of the digital soft-start, add a lowfrequency lead compensation network (Figure 5). The network effectively spreads out the switching pulses and lowers the peak inductor currents.
The smoothing network is active only during soft-start when the output voltage rises. Positive changes in the output are instantaneously coupled to the FB pin through D1 and feed-forward capacitor C2. This arrangement generates a smoothly rising output voltage. When the output voltage reaches regulation, C2 charges up through R3 and D1 turns off. In most applications, the lead compensation is not needed and can be disabled by making R3 large. With R3 > R2, the pole and the zero in the compensation network are very close to one another and cancel out.

# Triple-Output TFT LCD Power Supply with Fault Protection 

## Input Capacitor

The input capacitor ( CIN ) reduces the current peaks drawn from the input supply and reduces noise injection into the device. Two $3.3 \mu \mathrm{~F}$ ceramic capacitors are used in the standard application circuit (Figure 1) because of the high source impedance seen in typical lab setups. Actual applications usually have much lower source impedance since the step-up regulator typically runs directly from the output of another regulated supply. Typically, CIN can be reduced below the values used in the standard applications circuit. Ensure a low noise supply at the IN pin by using adequate CIN. Alternatively, greater voltage variation can be tolerated on CIN if IN is decoupled from CIN using an RC lowpass filter (see R1, C1 in Figure 1).

Rectifier Diode
The MAX1889's high switching frequency demands a high-speed rectifier. Schottky diodes are recommended for most applications because of their fast recovery time and low forward voltage. In general, a 1A Schottky diode complements the internal MOSFET well.

## Input P-Channel MOSFET

Select the input P-channel MOSFET based on the current rating, voltage rating, gate threshold, and on-resistance. The MOSFET must be able to handle the peak input current (see the Inductor Selection section). The drain-to-source voltage rating of the input MOSFET should be higher than the maximum input voltage. Because the MOSFET conducts the full input current, the on-resistance should be low enough for higher efficiency. Use a low-threshold MOSFET to ensure that the switch is fully enhanced at lowest input voltages.

## Setting the Input Overcurrent Threshold

The high-side comparator of the MAX1889 provides input overcurrent protection when used in conjunction with an external P-channel MOSFET P1. The accuracy of the overcurrent threshold is affected by many factors, including comparator offset, resistor tolerance, input voltage range, and variations in MOSFET RDS(ON). The input overcurrent comparator is only intended to protect against catastrophic failures. This function is similar to an input fuse.
To minimize the impact of the comparator's input offset on the current-sense accuracy, the sense voltage should be close to the upper limit of the common-mode range, which extends up to $80 \%$ of the input voltage. The resistive voltage-divider (R3/R4), combined with the on-state resistance of P1, sets the overcurrent threshold. The center of R3/R4 is connected to the inverting input (OCN) as shown in Figure 6.

If the comparator and resistors are ideal, the threshold is at the current where both inputs are equal:

$$
V_{I N} \times \frac{R 2}{R 1+R 2}=\left(V_{I N}-l_{L(M A X)} \times R_{D S}(M A X)\right) \times \frac{R 4}{R 3+R 4}
$$

$\mathrm{l}(\mathrm{MAX})$ is the average inductor current at maximum load condition and minimum input voltage, and given by:

$$
I_{\mathrm{L}(\mathrm{MAX})}=\frac{V_{\text {OUT }}}{\eta \times V_{\operatorname{IN(MIN)}}} \times I_{\mathrm{LOAD}(\mathrm{MAX})}
$$

where $\eta$ is the efficiency of the main step-up regulator. If the step-up regulator's minimum input voltage is 2.7 V , output voltage is 9 V and maximum load current is 0.3 A . Assuming 80\% efficiency, the maximum average inductor current is:

$$
I_{L(M A X)}=\frac{9 V}{0.8 \times 2.7 V} \times 0.3 \mathrm{~A}=1.25 \mathrm{~A}
$$

RDS(MAX) is the maximum on-state drain-to-source resistance of P 1 . The maximum $\mathrm{RDS}(\mathrm{ON})$ at $+25^{\circ} \mathrm{C}$ can be found in the MOSFET data sheet, but that number does not include the temperature coefficient.
Since the temperature coefficient for the resistance is $0.5 \% /{ }^{\circ} \mathrm{C}, \mathrm{RDS}(\mathrm{MAX})$ can be calculated with the following equation:

$$
\mathrm{R}_{\mathrm{DS}(\mathrm{MAX})}=\mathrm{R}_{\mathrm{DS}} 25^{\circ} \mathrm{C} \times\left[1+0.005 \times\left(\mathrm{T}_{\mathrm{J}}-25\right)\right]
$$

where $T_{J}$ is the actual MOSFET junction temperature in normal operation due to ambient temperature rise and self-heating caused by power dissipation. As an example, consider Fairchild FDN304P, which has a maximum $\operatorname{RDS}(O N)$ at room temperature of $70 \mathrm{~m} \Omega$.


Figure 6. Setting the Overcurrent Threshold

## Triple-Output TFT LCD Power Supply with Fault Protection

If the junction temperature is $+100^{\circ} \mathrm{C}$, the maximum onstate resistance overtemperature is:

$$
R_{D S(\operatorname{MAX})}=70 \mathrm{~m} \Omega \times[1+0.005 \times(100-25)]=100 \mathrm{~m} \Omega
$$

For given R1 and R2 values, the ideal ratio of R3/R4 can be determined:

$$
\frac{R 3}{R 4}=\frac{R 1+R 2}{R 2} \times \frac{V_{I N}-\operatorname{PEAK}(M A X)}{} \times R_{\text {DS }}(M A X) ~(1
$$

To consider the effect of resistor tolerance, comparator offset, and input voltage variation, the minimum threshold equation is:

$$
\begin{aligned}
& V_{\mathrm{IN}(\mathrm{MIN})} \times \frac{\mathrm{R} 2 \times(1+\varepsilon)}{\mathrm{R} 1 \times(1-\varepsilon)+\mathrm{R} 2 \times(1+\varepsilon)}+5 \mathrm{mV}= \\
& \left(\mathrm{V}_{\mathrm{IN}(\mathrm{MIN})}-\mathrm{l}_{\mathrm{L}(\mathrm{MAX})} \times \mathrm{R}_{\mathrm{DS}(\mathrm{MAX})}\right) \times \frac{\mathrm{R} 4 \times(1-\varepsilon)}{\mathrm{R} 3 \times(1+\varepsilon)+\mathrm{R} 4 \times(1-\varepsilon)}
\end{aligned}
$$

where $\operatorname{VIN}(\operatorname{MIN})$ is the minimum expected value of the input voltage, $\varepsilon$ is the tolerance of the resistors and the 5 mV is the worst-case input offset voltage of the comparator. To simplify the equation, define a constant $k$ as follows:

$$
k=\frac{1-\varepsilon}{1+\varepsilon}
$$

The minimum threshold equation becomes:

$$
\begin{aligned}
& V_{I N(M I N)} \times \frac{R 2}{k \times R 1+R 2}+5 m V= \\
& \left(V_{I N(M I N)}{ }^{-1} L(M A X) \times R_{D S(M A X)}\right) \times \frac{k \times R 4}{R 3+k \times R 4}
\end{aligned}
$$

Solving for R3/R4 yields:

$$
\frac{\mathrm{R} 3}{\mathrm{R} 4}=k \times\left(\frac{\mathrm{V}_{\mathrm{IN}(\mathrm{MIN})}-\mathrm{I}(\mathrm{MAX}) \times \mathrm{R}_{\mathrm{DS}(\mathrm{MAX})}}{\mathrm{V}_{\mathrm{IN}(\mathrm{MIN})} \times \frac{\mathrm{R} 2}{\mathrm{R} 2+\mathrm{k} \times \mathrm{R} 1}+5 \mathrm{mV}}-1\right)
$$

The R3/R4 ratio guarantees the required minimum level for IL(MAX). The typical overcurrent threshold is given by:

$$
\mathrm{I}_{\text {TH_ }} \text { TYP }=\frac{\mathrm{V}_{\mathrm{IN}(T Y P)}}{\mathrm{R}_{\mathrm{DS}(\text { TYP })}} \times\left[1-\frac{\mathrm{R} 2 \times(\mathrm{R} 3+\mathrm{R} 4)}{\mathrm{R} 4 \times(\mathrm{R} 1+\mathrm{R} 2)}\right]
$$

The following example shows how to apply the above equations in the design. If $1 \%$ resistors are used, then $\varepsilon=0.01$. To set $\mathrm{V}_{\text {OCP }}$ to be around $75 \%$ of $\mathrm{V}_{\mathrm{IN}}$, select $R 1=51.1 \mathrm{k} \Omega$ and $R 2=150 \mathrm{k} \Omega$. Assume that the minimum input voltage is 2.7 V and the typical input voltage is 3.3 V , the average inductor current at maximum load is 1.25 A , and the maximum $\mathrm{R}_{\mathrm{DS}}(\mathrm{ON})$ of P 1 is $100 \mathrm{~m} \Omega$ :

$$
k=\frac{1-0.01}{1+0.01}=0.9802
$$

$$
\begin{aligned}
\frac{\mathrm{R} 3}{\mathrm{R} 4} & =0.9802 \times\left(\frac{2.7 \mathrm{~V}-1.25 \mathrm{~A} \times 0.1 \Omega}{2.7 \mathrm{~V} \times \frac{150 \mathrm{k} \Omega}{150 \mathrm{k} \Omega+0.9802 \times 51.1 \mathrm{k} \Omega}+0.005 \mathrm{~V}}-1\right) \\
& =0.2637
\end{aligned}
$$

If R4 $=150 \mathrm{k} \Omega$, then $\mathrm{R} 3=39.2 \mathrm{k} \Omega$. The typical overcurrent threshold is:

$$
\begin{aligned}
\mathrm{I}_{\mathrm{TH}}^{-} \text {TYP } & =\frac{3.3 \mathrm{~V}}{0.047 \Omega} \times\left[1-\frac{150 \mathrm{k} \Omega \times(39.2 \mathrm{k} \Omega+150 \mathrm{k} \Omega)}{150 \mathrm{k} \Omega \times(51.1 \mathrm{k} \Omega+150 \mathrm{k} \Omega)}\right] \\
& =4.15 \mathrm{~A}
\end{aligned}
$$

## Charge Pumps

## Selecting the Number of Charge-Pump Stages

For highest efficiency, always choose the lowest number of charge-pump stages that meets the output requirement.
The number of positive charge-pump stages is given by:

$$
N_{\text {POS }}=\frac{V_{\text {PL }}+V_{\text {DROPOUT }}-V_{\text {MAIN }}}{V_{\text {MAIN }}-2 \times V_{D}}
$$

where NpOS is the number of positive charge-pump stages, VPL is the positive linear-regulator output, $V_{\text {MAIN }}$ is the main step-up regulator output, $V_{D}$ is the forward voltage drop of the charge-pump diode, and VDROPOUT is the dropout margin for the linear regulator. Use VDROPOUT $=2 \mathrm{~V}$.

# Triple-Output TFT LCD Power Supply with Fault Protection 

The number of negative charge-pump stages is given by:

$$
\mathrm{N}_{\mathrm{NEG}}=\frac{-\mathrm{V}_{\mathrm{NL}}+\mathrm{V}_{\mathrm{DOPOUT}}}{\mathrm{~V}_{\mathrm{MAIN}}-2 \times \mathrm{V}_{\mathrm{D}}}
$$

where NNEG is the number of negative charge-pump stages, $\mathrm{V}_{\mathrm{NL}}$ is the negative linear-regulator output, $V_{\text {MAIN }}$ is the main step-up regulator output, $V_{D}$ is the forward voltage drop of the charge-pump diode, and VDROPOUT is the dropout margin for the linear regulator. Use VDROPOUT = 2 V .
The above equations are derived based on the assumption that the first stage of the positive charge pump is connected to VMAIN and the first stage of the negative charge pump is connected to ground. Sometimes fractional stages are more desirable for better efficiency. This can be done by connecting the first stage to VIN or another available supply.
If the first charge-pump stage is powered from VIN, then the above equations become:

$$
\begin{aligned}
& N_{\text {POS }}=\frac{V_{\text {PL }}+V_{\text {DROPOUT }}-V_{I N}}{V_{M A I N}-2 \times V_{D}} \\
& N_{\text {NEG }}=\frac{-V_{\text {NL }}+V_{\text {DROPOUT }}+V_{I N}}{V_{\text {MAIN }}-2 \times V_{D}}
\end{aligned}
$$

Flying Capacitor
Increasing the flying capacitor (CX) value increases the output current capability. Increasing the capacitance indefinitely has a negligible effect on output current capability because the internal switch resistance and the diode impedance limit the source impedance. A $0.1 \mu \mathrm{~F}$ ceramic capacitor works well in most low-current applications. The flying capacitor's voltage rating must exceed the following:

$$
\mathrm{V}_{\mathrm{CX}}>\mathrm{N} \times \mathrm{V}_{\text {MAIN }}
$$

where N is the stage number in which the flying capacitor appears, and VMAIN is the main output voltage. For example, the two-stage positive charge pump in the typical application circuit (Figure 1) where VMAIN $=9 \mathrm{~V}$ contains two flying capacitors. The flying capacitor in the first stage (C14) requires a voltage rating over 9V. The flying capacitor in the second stage (C13) requires a voltage rating over 18 V .

## Charge-Pump Output Capacitor

Increasing the output capacitance or decreasing the ESR reduces the output ripple voltage and the peak-topeak transient voltage. With ceramic capacitors, the
output voltage ripple is dominated by the capacitance value. Use the following equation to approximate the required capacitor value:

$$
C_{\text {OUT }} \geq \frac{\mathrm{L}_{\text {LOAD }}}{2 \mathrm{fOSC}_{\mathrm{OIPPLE}}}
$$

where $\mathrm{V}_{\text {RIPPLE }}$ is the peak-to-peak value of the output ripple.

Charge-Pump Rectifier Diodes
Use Schottky diodes with a current rating equal to or greater than two times the average charge-pump input current.

## Linear-Regulator Controllers

## Output Voltage Selection

Adjust the positive linear-regulator output voltage by connecting a resistive voltage-divider from VPL to GND with the center tap connected to FBP (Figure 1). Select R13 in the range of $10 \mathrm{k} \Omega$ to $30 \mathrm{k} \Omega$.
Calculate R12 with the following equation:

$$
R 12=R 13\left[\left(V_{P L} / V_{F B P}\right)-1\right]
$$

where $\mathrm{V}_{\mathrm{FBP}}=1.25 \mathrm{~V}$.
Adjust the negative linear-regulator output voltage by connecting a resistive voltage-divider from VNL to REF with the center tap connected to FBN (Figure 1). Select R10 in the range of $10 \mathrm{k} \Omega$ to $30 \mathrm{k} \Omega$. Calculate R9 with the following equation:

$$
\mathrm{R9}=\mathrm{R} 10\left[\left(\mathrm{~V}_{\mathrm{FBN}}-\mathrm{V}_{\mathrm{NL}}\right) /\left(\mathrm{V}_{\mathrm{REF}}-\mathrm{V}_{\mathrm{FBN}}\right)\right]
$$

where $\mathrm{V}_{\mathrm{FBN}}=125 \mathrm{mV}$, $\mathrm{V}_{\text {REF }}=1.25 \mathrm{~V}$. Note that REF is only guaranteed to source $50 \mu \mathrm{~A}$. Using a resistor less than $20 \mathrm{k} \Omega$ for R10 results in higher bias current than REF can supply. Connecting another resistor (R14) from VMAIN to REF (Figure 1) can solve this problem because the main output can supply part of the resistor's (R10) bias current. Use the following equation to determine the value of R14:

$$
R 14=\frac{V_{\text {MAIN }}-V_{\text {REF }}}{\left(\frac{V_{\text {REF }}-V_{\text {FBN }}}{R 10}\right)-40 \mu \mathrm{~A}}
$$

Drawing only $40 \mu \mathrm{~A}$ from REF leaves the remaining $10 \mu \mathrm{~A}$ for other purposes.

Pass Transistor Selection
The pass transistor must meet specifications for current gain ( $\beta$ ), input capacitance, collector-emitter saturation voltage, and power dissipation.

## Triple-Output TFT LCD Power Supply with Fault Protection

The transistor's current gain limits the guaranteed maximum output current to:

$$
\operatorname{LOAD}(\mathrm{MAX})=\left(\operatorname{ldRV}-\frac{V_{\mathrm{BE}}}{R_{\mathrm{BE}}}\right) \beta_{\mathrm{MIN}}
$$

where IDRV is the minimum base-drive current, and RBE is the pullup resistor connected between the transistor's base and emitter. Furthermore, the transistor's current gain increases the linear regulator's DC loop gain (see the Stability Requirements section), so excessive gain destabilizes the output. Therefore, transistors with current gain over 100 at the maximum output current are not recommended. The transistor's input capacitance and input resistance also create a second pole, which could be low enough to make the output unstable when heavily loaded.
The transistor's saturation voltage at the maximum output current determines the minimum input-to-output voltage differential that the linear regulator supports. Alternatively, the package's power dissipation could limit the usable maximum input-to-output voltage differential. The maximum power dissipation capability of the transistor's package and mounting must exceed the actual power dissipation in the device. The power dissipation equals the maximum load current times the maximum input-to-output voltage differential:

$$
\begin{aligned}
& P=\operatorname{lOAD}(\mathrm{MAX})\left(\mathrm{V}_{\text {LDOIN }}-\mathrm{V}_{\text {LDOOUT }}\right)= \\
& \operatorname{LOAD}(\mathrm{MAX}) \mathrm{V}_{\text {CE }}
\end{aligned}
$$

During startup, the LDO outputs are below their respective setpoints, and the base drive to the pass transistors is a maximum. The large drive currents can cause the charge-pump outputs to collapse. If the chargepump loading is objectionable, base resistors can be added between the drive outputs (DRVN and DRVP) and the pass transistors (Figure 7). These resistors limit the maximum drive current and prevent discharging the charge pump's output capacitors. Select the minimum base drive current to meet the maximum required LDO output current:

$$
\mathrm{I}_{\text {DRIVE(MIN })}=\frac{\mathrm{I}_{\text {LDOOUT(MAX) }}}{\beta_{\mathrm{MIN}}}
$$

The resistance required to guarantee this base current is:

$$
\begin{aligned}
& R_{\text {BASE }} \leq \frac{V_{\text {LDOIN(MAX) }}-V_{\text {BE }}}{\operatorname{ldRIVE(MIN)~}} \\
& =\frac{\beta_{\text {MIN }}\left(V_{\text {LDOIN(MAX) }}-V_{B E}\right)}{\left.\operatorname{LDOOOUT}^{\text {(MAX }}\right)}
\end{aligned}
$$

As a consequence of adding the base resistors, a voltage change at DRVN and DRVP accompanies changes in drive current. This voltage change can be coupled through parasitic capacitance to the LDO feedback pins. If the rate of voltage change is sufficiently large, it can cause instability.


Figure 7. Limiting LDO Drive Current During Startup

# Triple-Output TFT LCD Power Supply with Fault Protection 

To avoid excessive voltage coupling, a small capacitor can be added in parallel with the base resistor. The resulting RC time constant should be between $5 \mu \mathrm{~s}$ to $50 \mu \mathrm{~s}$.

## Stability Requirements

The MAX1889 linear-regulator controllers use an internal transconductance amplifier to drive an external pass transistor. The transconductance amplifier, the pass transistor, the base-emitter resistor, and the output capacitor determine the loop stability. If the output capacitor and pass transistor are not properly selected, the linear regulator can be unstable.
The transconductance amplifier regulates the output voltage by controlling the pass transistor's base current. The total DC loop gain is approximately:

$$
\left.\left.A_{V(L D O)}=\left(\frac{5.5}{V_{T}}\right)\left[1+\left(\frac{I_{\mathrm{BIASh}}^{\mathrm{FE}}}{}\right)\right] \mathrm{I}_{\mathrm{LOAD}}\right)\right]
$$

where $\mathrm{V}_{\mathrm{T}}$ is 26 mV at room temperature, and $\mathrm{I}_{\mathrm{BI}}$ AS is the current through the base-to-emitter resistor ( $\mathrm{R}_{\mathrm{BE}}$ ). This bias resistor is typically $3 \mathrm{k} \Omega$, providing 0.23 mA of current, biasing the LDO near its regulation voltage setpoint.

The output capacitor and the load resistance create the dominant pole in the system. The pass transistor's input capacitance creates a second pole in the system. Additionally, the output capacitor's ESR generates a zero.
To achieve stable operation, use the following equations to verify that the linear regulator is properly compensated:

1) First, determine the dominant pole set by the linear regulator's output capacitor and the load resistor:

$$
f_{\text {POLE(CLDO) }}=\frac{1}{2 \pi C_{L D O} R_{\text {LOAD }}}=\frac{\operatorname{LLOAD}_{\text {LOAX }}}{2 \pi C_{\text {LDO }} V_{\text {LDO }}}
$$

The unity gain crossover of the linear regulator is:

$$
\text { fCROSSOVER }=A V(L D O) \text { fPOLE(CLDO) }
$$

2) Next, determine the second pole set by the base-to-emitter capacitance (including the transistor's input capacitance), the transistor's input resistance, and the base-to-emitter pullup resistor:

$$
\begin{aligned}
\mathrm{f}_{\mathrm{POLE}(\mathrm{CBE})} & =\frac{1}{2 \pi \mathrm{C}_{\mathrm{BE}}\left(\mathrm{R}_{\mathrm{BE}} I I \mathrm{R}_{\mathrm{IN}}\right)} \\
& =\frac{R_{\mathrm{BE}} l_{\mathrm{LOAD}}+\mathrm{V}_{\mathrm{T}} \mathrm{~h}_{\mathrm{FE}}}{2 \pi \mathrm{C}_{\mathrm{BE}} \mathrm{R}_{\mathrm{BE}} \mathrm{~V}_{\mathrm{T}} \mathrm{~h}_{\mathrm{FE}}}
\end{aligned}
$$

3) A third pole is set by the linear regulator's feedback resistance and the capacitance (including stray capacitance) between FB_ and GND (for the positive LDO) and FBN and GND (for the negative LDO) (Figure 8):

$$
\begin{aligned}
& \mathrm{f}_{\mathrm{POLE}(\mathrm{FB})_{-} \mathrm{POS}}=\frac{1}{2 \pi \mathrm{C}_{\mathrm{FB}}(\mathrm{R} 12 \| \mathrm{R} 13)} \\
& \mathrm{f}_{\mathrm{POLE}(\mathrm{FB})_{-} \mathrm{NEG}}=\frac{1}{2 \pi \mathrm{C}_{\mathrm{FB}}(\mathrm{R} 9 \| \mathrm{R} 10)}
\end{aligned}
$$

4) If the second and third poles occur well after unitygain crossover, the linear regulator remains stable:

However, if the ESR zero occurs before the unity-gain crossover, cancel the zero with the feedback pole by changing circuit components such that:

$$
\mathrm{f}_{\mathrm{POLE}(\mathrm{FB})} \approx \frac{1}{2 \pi \mathrm{C}_{\mathrm{OUT}} \mathrm{R}_{\mathrm{ESR}}}
$$

For most applications where ceramic capacitors are used, the ESR zero always occurs after the crossover.
A capacitor connected between the output and the feedback node improves the transient response, reduces the noise coupled into the feedback loop, and maintains the correct regulation point (Figure 8).

## Output Capacitor Selection

Typically, more output capacitance provides the best solution, since this also reduces the output voltage drop immediately after a load transient. Connect at least a $0.1 \mu \mathrm{~F}$ capacitor between the linear regulator's output and ground, as close to the external pass transistor as possible. Depending on the selected pass transistor, larger capacitor values may be required for stability (see the Stability Requirements section). Furthermore, the output capacitor's ESR affects stability. Use output capacitors with an ESR less than $200 \mathrm{~m} \Omega$ to ensure stability and optimum transient response. Once the minimum capacitor value for stability is determined, verify that the linear regulator's output does not contain excessive noise. Although adequate for stability, small capacitor values can provide too much bandwidth, making the linear regulator sensitive to noise. Larger capacitor values reduce the bandwidth, thereby reducing the regulator's noise sensitivity. If noise on the ground reference causes the design to be marginally stable for the negative linear regulator, bypass the negative output back to its reference voltage. This technique reduces the differential noise on the output.

# Triple-Output TFT LCD Power Supply with Fault Protection 

## Applications Information

PC Board Layout
Careful PC board layout is extremely important for proper operation. Use the following guidelines for good PC board layout:

1) Minimize the area of high-current loops by placing the input capacitors, inductor, output diode, and output capacitors less than 0.2in ( 5 mm ) from the LX and PGND pins. Connect these components with traces as wide as possible. Avoid using vias in the high-current paths. If vias are unavoidable, use many vias in parallel to reduce resistance and inductance.
2) Create islands for the analog ground (GND), power ground (PGND), and linear regulator ground. Starconnect them to the backside pad of the device. The REF bypass capacitor and both feedback dividers should be connected to the analog ground island (GND). The step-up regulator's input and output capacitors, and the charge-pump components should be a wide power ground plane. The power ground plane should be connected to the power ground pin (PGND) with a wide trace. Maximizing the width of the power ground traces improves efficiency and reduces output voltage ripple and noise
spikes. All the other ground connections, such as the IN pin bypass capacitor and the linear regulator output capacitors, should be star-connected to the backside of the device with wide traces. Make no other connections between these separate ground planes.
3) Place IN pin and REF pin bypass capacitors as close to the device as possible.
4) Place all feedback voltage-divider resistors as close to their respective feedback pins as possible. The divider's center trace should be kept short. Placing the resistors far away causes their FB traces to become antennas that can pick up switching noise. Care should be taken to avoid running any feedback trace near LX or the switching nodes in the charge pumps.
5) Minimize the length and maximize the width of the traces between the output capacitors and the load for best transient responses.
6) Minimize the size of $L X$ node while keeping it wide and short. Keep the LX node away from feedback nodes (FB, FBP, and FBN) and analog ground. Use DC traces as shield if necessary.
Refer to the MAX1889 evaluation kit for an example of proper board layout.


Figure 8. LDO Compensation

# Triple-Output TFT LCD Power Supply with Fault Protection 

## Additional Application Circuits Operation with Output Voltage $>13 \mathrm{~V}$

The maximum output voltage of the step-up regulator is 13 V , which is limited by the absolute maximum rating of the internal power MOSFET. To achieve higher output voltage, an external N -channel MOSFET can be cascoded with the internal FET (Figure 9). Since the gate of the external FET is biased from the input supply, use a logic-level FET to ensure that the FET is fully enhanced at the minimum input voltage. The current rating of the FET needs to be higher than the internal current limit.

Changing Power-Up Sequence The power-up sequencing of the linear regulators can be controlled using external delays. Figure 10 shows an application where the negative linear-regulator output powers up with a certain delay after the positive linear regulator reaches regulation. The resistors R1, R2, and the capacitor $C$ form an RC network that provides the power-up delay. The time constant of this RC network is:

$$
\tau=\frac{\mathrm{R} 1 \times \mathrm{R} 2}{\mathrm{R} 1+\mathrm{R} 2} \mathrm{C}
$$

Select the ratio of R1 and R2 so that:

$$
V_{N} \frac{R 2}{R 1+R 2}+V_{P L} \frac{R 1}{R 1+R 2}=0
$$

or:

$$
\frac{R 1}{R 2}=-\frac{V_{N}}{V_{P L}}
$$

With this R1/R2 ratio, the power-up delay can be calculated as:

$$
\tau_{\mathrm{D}}=\tau \ln \left(\frac{\mathrm{V}_{\mathrm{PL}} \frac{\mathrm{R} 1}{\mathrm{R} 1+\mathrm{R} 2}}{\mathrm{~V}_{\mathrm{D}}-0.125 \mathrm{~V}}\right)
$$

where $V_{D}$ is the forward voltage drop of the diode and 0.125 V is the FBN regulation point.

As a design example, assume the positive linear-regulator output VPL is +20 V , the negative charge-pump output $\mathrm{V}_{\mathrm{N}}$ is -9 V , and the required power-up delay time tD is 4 ms :

$$
\frac{\mathrm{R} 1}{\mathrm{R} 2}=\frac{9}{20}
$$



Figure 9. Operation with Output Voltage > 13V Using Cascoded MOSFET

The required RC time constant is:


Choose $C=0.1 \mu F$, then $R 1 / / R 2=16.8 \mathrm{k} \Omega$. Use standard resistor values: $\mathrm{R} 1=56 \mathrm{k} \Omega$ and $\mathrm{R} 2=24 \mathrm{k} \Omega$.

Disabling Input MOSFET Switch
If the input protection MOSFET is not needed, disable the input overcurrent comparator by connecting the OCP pin to ground, the OCN pin to VIN. Leave the GATE pin floating (Figure 11).

Generating Gamma Reference Voltage
The reference voltage for the Gamma correction resistor string can be produced using the linear-regulator controller. If the voltage difference between the main boost voltage (VMAIN) and the Gamma reference voltage is 400 mV or greater, the emitter of the PNP pass transistor should be connected to $\mathrm{V}_{\text {MAIN }}$.

## Triple-Output TFT LCD Power Supply with Fault Protection



Figure 10. Controlling Power-Up Sequence with External Delay

If the voltage difference is less than 400 mV , then the emitter of the PNP should be connected to a high supply voltage. The Vp output has two charge-pump stages added to VMain. The emitter of the PNP can be connected to the output of the first stage as shown in Figure 12. For higher efficiency, the first charge-pump stage can be connected to VIN rather than VMAIN, as this reduces the power loss.

Chip Information
TRANSISTOR COUNT: 2396 PROCESS: BiCMOS

## Triple-Output TFT LCD Power Supply with Fault Protection



Figure 11. Disabling Input Protection MOSFET Switch

## Triple-Output TFT LCD Power Supply with Fault Protection



Figure 12. Generating Gamma Reference Voltage
$\qquad$

## Triple-Output TFT LCD Power Supply with Fault Protection

## Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)


## Triple-Output TFT LCD Power Supply with Fault Protection

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)

| COMMON DIMENSIONS |  |  |  |  |  |  |  |  |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| PKG | 16L 5x5 |  |  | 20L 5x5 |  |  | 28L 5x5 |  |  | 32L 5x5 |  |  |
| SYMBOL | MIN. | NOM. | MAX. | MIN. | NOM. | MAX. | MIN. | NOM. | MAX. | MIN. | NOM. | MAX. |
| A | 0.80 | 0.90 | 1.00 | 0.80 | 0.90 | 1.00 | 0.80 | 0.90 | 1.00 | 0.80 | 0.90 | 1.00 |
| A1 | 0.00 | 0.01 | 0.05 | 0.00 | 0.01 | 0.05 | 0.00 | 0.01 | 0.05 | 0.00 | 0.01 | 0.05 |
| A2 | 0.00 | 0.65 | 1.00 | 0.00 | 0.65 | 1.00 | 0.00 | 0.65 | 1.00 | 0.00 | 0.65 | 1.00 |
| A3 | 0.20 REF |  |  | 0.20 REF |  |  | 0.20 REF |  |  | 0.20 REF |  |  |
| b | 0.28 | 0.33 | 0.40 | 0.23 | 0.28 | 0.35 | 0.18 | 0.23 | 0.30 | 0.18 | 0.23 | 0.30 |
| D | 4.90 | 5.00 | 5.10 | 4.90 | 5.00 | 5.10 | 4.90 | 5.00 | 5.10 | 4.90 | 5.00 | 5.10 |
| D1 | 4.75 BSC |  |  | 4.75 BSC |  |  | 4.75 BSC |  |  | 4.75 BSC |  |  |
| E | 4.90 | 5.00 | 5.10 | 4.90 | 5.00 | 5.10 | 4.90 | 5.00 | 5.10 | 4.90 | 5.00 | 5.10 |
| E1 | 4.75 BSC |  |  | 4.75 BSC |  |  | 4.75 BSC |  |  | 4.75 BSC |  |  |
| e | 0.80 BSC |  |  | 0.65 BSC |  |  | 0.50 BSC |  |  | 0.50 BSC |  |  |
| k | 0.25 | - | - | 0.25 | - | - | 0.25 | - | - | 0.25 | - | - |
| L | 0.35 | 0.55 | 0.75 | 0.35 | 0.55 | 0.75 | 0.35 | 0.55 | 0.75 | 0.30 | 0.40 | 0.50 |
| N | 16 |  |  | 20 |  |  | 28 |  |  | 32 |  |  |
| ND | 4 |  |  | 5 |  |  | 7 |  |  | 8 |  |  |
| NE | 4 |  |  | 5 |  |  | 7 |  |  | 8 |  |  |
| P | 0.00 | 0.42 | 0.60 | 0.00 | 0.42 | 0.60 | 0.00 | 0.42 | 0.60 | 0.00 | 0.42 | 0.60 |
| $\theta$ | $0{ }^{\circ}$ |  | 12* | $0^{\circ}$ |  | $12^{\circ}$ | $0{ }^{\circ}$ |  | $12^{\circ}$ | $0^{\circ}$ |  | $12^{\circ}$ |


| EXPDSED PAD |  |  |  |  |  | VARIATIDNS |  |  |  |
| :--- | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| PKG. <br> CODES | D2 |  |  | E2 |  |  |  |  |  |
|  | MIN. | NDM. | MAX. | MIN. | NDM. | MAX. |  |  |  |
| G1655-3 | 2.95 | 3.10 | 3.25 | 2.95 | 3.10 | 3.25 |  |  |  |
| G2055-1 | 2.55 | 2.70 | 2.85 | 2.55 | 2.70 | 2.85 |  |  |  |
| G2055-2 | 2.95 | 3.10 | 3.25 | 2.95 | 3.10 | 3.25 |  |  |  |
| G2855-1 | 2.55 | 2.70 | 2.85 | 2.55 | 2.70 | 2.85 |  |  |  |
| G2855-2 | 2.95 | 3.10 | 3.25 | 2.95 | 3.10 | 3.25 |  |  |  |
| G3255-1 | 2.95 | 3.10 | 3.25 | 2.95 | 3.10 | 3.25 |  |  |  |

NOTES:

1. DIE THICKNESS ALLOWABLE IS 0.305 mm MAXIMUM ( .012 INCHES MAXIMUM)
2. DIMENSIONING \& TOLERANCES CONFORM TO ASME Y14.5M. - 1994.
3. $N$ is the number of terminals.

Nd IS THE NUMBER OF TERMINALS in X-DIRECTION \& Ne is THE NUMBER OF TERMINALS in Y-DIRECTION.
4. dimension b applies to plated terminal and is measured between 0.20 and 0.25 mm from terminal tip.
5. THE PIN \#1 IDENTIFIER MUST be existed on the top surface of the package by using indentation mark or ink/laser marked.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
7. ALL DIMENSIONS ARE IN MILLIMETERS.
8. PACKAGE WARPAGE MAX 0.05 mm .
9. APPLIED FOR EXPOSED PAD AND TERMINALS.

EXCLUDE EMBEDDED PART OF EXPOSED PAD FROM MEASURING.
10. MEETS JEDEC MO220.
11. this package outline applies to anvil singulation (stepped sides).

|  |  |  |  |
| :--- | :--- | :--- | :--- | :--- |

## Triple-Output TFT LCD Power Supply with Fault Protection

## Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)


## Triple-Output TFT LCD Power Supply with Fault Protection

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)


Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.

